

# **HMDX Jam Plus Micro USB Jack Replacement**

This guide provides steps for replacing a...

Written By: Maxwell Erickson



#### **INTRODUCTION**

This guide provides steps for replacing a damaged Micro USB Jack on the HMDX Jam Plus. This guide requires previous soldering skill and utilizes a Micro Soldering Iron. This guide is should not be attempted by beginners. If performed incorrectly the device may not function anymore.

#### TOOLS:

iFixit Opening Tool (1)
Phillips #1 Screwdriver (1)
Phillips #00 Screwdriver (1)
Micro Soldering Iron Hakko FM-2032-51
fits FM-203 206 (1)
Desoldering Braid (1)
Lead-Free Solder (1)

### Step 1 — Battery



- Flip the device over so the bottom is facing up.
- Use the large plastic opening tool to gently pry the rubber base from the device.
- Slowly move the plastic opening tool around the edge of the rubber base to separate it from the plastic.



• Use a Phillips #1 screwdriver to remove the four black 9mm screws from the device.

# Step 3



 Gently separate the base from the rest of the device to reveal the battery and the main board.



- Carefully use the plastic opening tool to remove the glue around the battery and speaker connectors.
- Pull gently on the connectors to separate each one from the main board.
- The battery is connected to board in the red socket and the speaker is connected in the white socket.

## Step 5



⚠ Batteries can be very dangerous if punctured. Use extra caution when using tools around the battery.

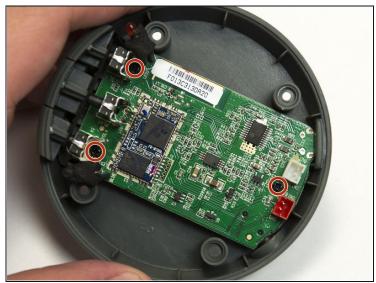
Use the plastic opening tool to gently pry the battery free from the rest of the device.





☑ Use new adhesive to secure battery back to the rest of the device.

# Step 7 — Micro USB Jack





• Remove the three black 6mm screws from the main board using a Philips #00 screwdriver.





- Carefully lift the main board away from the plastic.
- Lift the side with the buttons first and be careful not to damage the Line In Jack or the Micro USB Jack.

## Step 9



- Use the Micro soldering iron to heat up each pad and use the desoldering wick to wick up the melted solder.
- The surface mount jack should pull from the surface without much force. Use <u>tweezers</u> to apply upward pressure on on the jack.
- △ Do not apply too much heat to the board as it may damage other portions of the board.

To reassemble your device, follow these instructions in reverse order.